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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

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HSB226WK

Silicon Schottky Barrier Diode

ADE-208-827 (Z)

Rev. 0
Nov. 1999

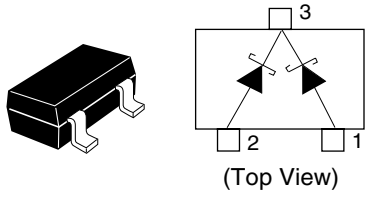
Features

- Low reverse current, Low capacitance.
- CMPAK Package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Code
HSB226WK	E6	CMPAK

Pin Arrangement



(Top View)

1 Anode
2 Anode
3 Cathode

Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Repetitive peak reverse voltage	V_{RRM}	25	V
Non-Repetitive peak forward surge current	I_{FSM} [*1*2]	200	mA
forward current	I_F [*2]	50	mA
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55 to +125	°C

Notes: 1. 10msec sine wave 1 pulse

Notes: 2. Two device total

Electrical Characteristics

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	V_{F1}	—	—	0.33	V	I_F = 1 mA
	V_{F2}	—	—	0.38	V	I_F = 5 mA
Reverse current	I_R	—	—	0.45	μA	V_R = 20V
Capacitance	C	—	—	2.80	pF	V_R = 1V, f = 1 MHz

Note: 1. Per one device

Main Characteristic

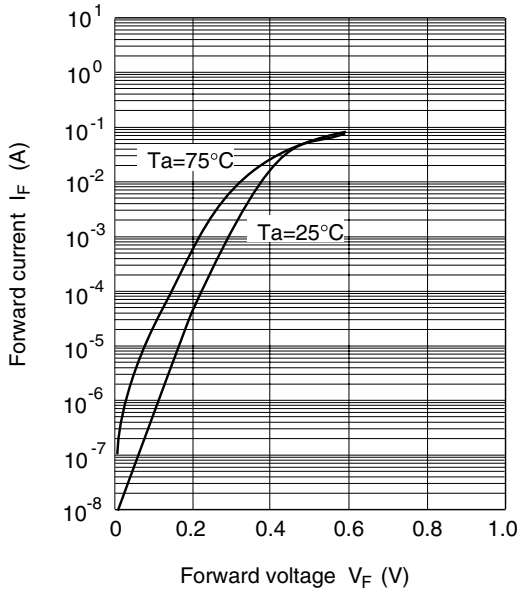


Fig.1 Forward current Vs. Forward voltage

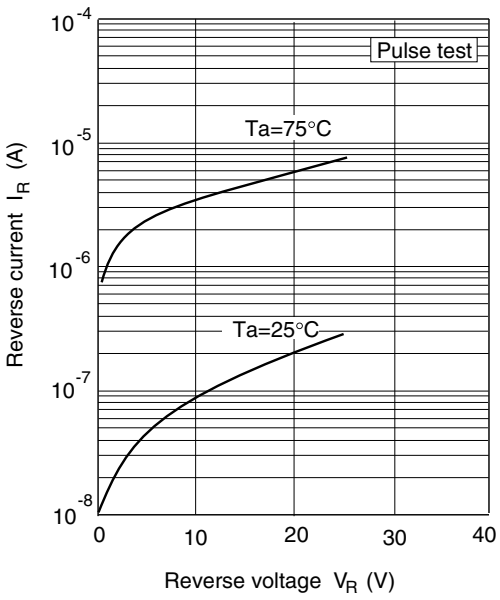


Fig.2 Reverse current Vs. Reverse voltage

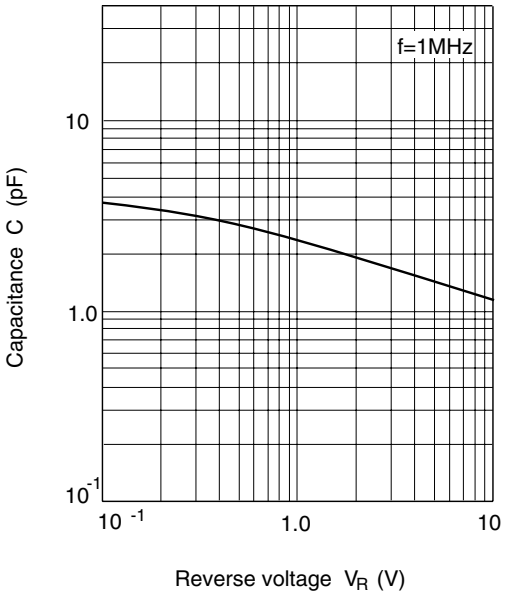
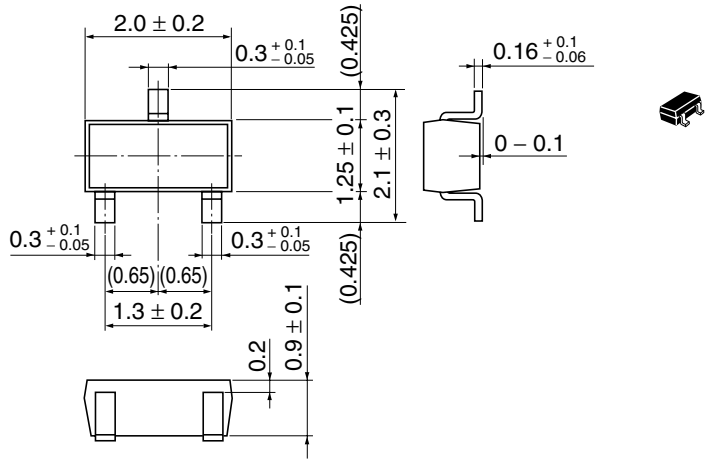


Fig.2 Capacitance Vs. Reverse voltage

Package Dimensions

Unit: mm



Hitachi Code	CMPAK
JEDEC	—
EIAJ	Conforms
Mass (reference value)	0.006 g

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